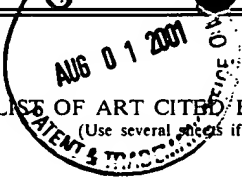


Form PTO-1449		 U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE			ATTY. DOCKET NO. M122-1694		SERIAL NO. 09/885,393	
LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)					APPLICANT Micron Technology, Inc.			
					FILING DATE June 19, 2001		GROUP 1756	
U.S. PATENT DOCUMENTS								
*Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate		
KAD	AA	4,474,975	10/2/84	Clemons et al.	—	—		
	AB	5,962,581	10/5/99	Hayase et al.	—	—		
	AC	5,677,015	10/14/97	Hasegawa	—	—		
	AD	5,783,493	7/21/98	Yeh et al.	—	—		
	AE	5,807,660	9/15/98	Lin et al.	—	—		
	AF	4,833,096	5/23/89	Huang et al.	—	—		
	AG	5,405,489	4/11/95	Kim et al.	—	—		
	AH	5,470,772	11/28/95	Woo	—	—		
	AI	5,652,187	7/29/97	Kim et al.	—	—		
	AJ	5,656,337	8/12/97	Park et al.	—	—		
FOREIGN PATENT DOCUMENTS								
	Document Number	Date	Country	Class	Subclass	Translation		
						Yes	No	
KAD	AK	0 942330	9/99	EPO	—	—		
KAD	AL	9 050993	2/97	Japan	—	—		
KAD	AM	406244172	9/94	Japan	—	—		
KAD	AN	593,727	10/47	GB	—	—		
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)								
KAD	AO	✓	Weidman, T. et al., "New Photodefinable Glass Etch Masks for Entirely Dry Photolithography: Plasma Deposited Organosilicon Hydride Polymers", Appl. Phys. Lett., Vol. 62, No. 4, Jan. 25, 1993, pp. 372-374.					
KAD	AP	✓	Weidman, T. et al., "All Dry Lithography: Applications of Plasma Polymerized Methylsilane as a Single Layer Resist and Silicon Dioxide Precursor", J. Photopolym. Sci. Technol., Vol. 8, No. 4, 1995, pp. 679-686.					
KAD	AQ	✓	Joubert, O. et al., "Application of Plasma Polymerized Methylsilane in an All Dry Resist Process for 193 and 248nm Lithography", Microelectronic Engineering 30 (1996), pp. 275-278.					
EXAMINER <i>K. Duda</i>				DATE CONSIDERED <i>8-5-02</i>				
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.								

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June 19, 2001GROUP
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*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
KAD	AA	4,805,683	2/21/89	Magdo et al.	—	—	
	AB	5,874,367	2/23/99	Dobson	—	—	
	AC	5,858,880	1/12/99	Dobson et al.	—	—	
	AD	5,219,613	6/15/93	Fabry et al.	—	—	
	AE	5,270,267	12/14/93	Ouellet	—	—	
	AF	5,541,445	7/30/96	Quellet	—	—	
	AG	6,022,404	2/8/00	Ettlinger et al.	—	—	
	AH	5,709,741	1/20/98	Akamatsu et al.	—	—	
	AI	4,648,904	3/10/87	DePasquale et al.	—	—	
KAD	AJ	4,158,717	6/19/79	Nelson	—	—	

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		Document Number	Date	Country	Class	Subclass	Translation	
							Yes	No
	AK	5-263 255	10/93	Japan	—	—		X
KAD	AL	0 464515	1/92	EPO	—	—		
KAD	AM	0 771886	5/97	EPO	—	—		
KAD	AN	63-157443	6/88	JP	—	—		
	AO	06 067019	3/94	JP (abstract)	—	—		

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)

KAD	AP	✓	McClatchie, S. et al., "Low Dielectric Constant Flowfill" Technology for IMD Applications", Proceed. of 3d Internatl. Dielectrics for ULSI Multilevel Interconnection Conf, Santa Clara, CA, Feb. 1997, pp. 34-40.
KAD	AQ	✓	Beekman, K. et al., "Sub-Micron Gap Fill and In-Situ Planarisation Using Flowfill™ Technology", ULSI Conf, Portland, OR, Oct. 1995, pp. 1-7.
	AR	✓	Kiermasz, A. et al., "Planarisation for Sub-Micron Devices Utilising a New Chemistry", DUMIC Conf., California, Feb. 1995, pp. 1-2.

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June 19, 2001GROUP
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*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
1017	AA	5,667,015	9/16/97	Harestad et al.	/	/	
	AB	5,661,093	8/26/97	Ravi et al.	/	/	
	AC	5,536,857	7/16/96	Narula et al.	/	/	
	AD	4,695,859	9/22/87	Guha et al.	/	/	
	AE	5,061,509	10/29/91	Naito et al.	/	/	
	AF	4,600,671	7/15/86	Saitoh et al.	/	/	
	AG	5,753,320	5/19/98	Mikoshiba et al.	/	/	
	AH	5,356,515	10/18/94	Tahara et al.	/	/	
	AI	6,054,379	4/25/00	Yau et al.	/	/	
	AJ	5,948,482	9/7/99	Brinker et al.	/	/	
1017	AK	5,800,877	9/1/98	Maeda et al.	/	/	

FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Subclass	Translation	
							Yes	No
	AL	20029	US99	Search Report				
	AM	20030	US99	Search Report				
	AN							
	AO							
	AP							

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)

1017	AQ		Bencher, C. et al., "Dielectric Antireflective Coatings for DUV Lithography", Solid State Technology, Mar. 1997, pp. 109-114.
1017	AR		Shibata, N., "Plasma-Chemical Vapor-Deposited Silicon Oxide/Silicon Oxynitride Double-Layer Antireflective Coating for Solar Cells", Jap. Journ. of Applied Physics, Vol. 30, No. 5, May 1991, pp. 997-1001.
1017	AS		McKenzie, D., et al., "New Technology for PACVD", Surface and Coatings Technology, Vol. 82, 1996, pp. 326-333.

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U.S. PATENT DOCUMENTS

*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
KAD	AA	5,260,600	11/9/93	Harada	/	/	
	AB	4,992,306	2/12/91	Hochberg et al.	/	/	
	AC	4,702,936	10/27/87	Maeda et al.	/	/	
	AD	4,863,755	9/5/89	Hess et al.	/	/	
	AE	5,234,869	8/10/93	Mikata et al.	/	/	
	AF	5,302,366	4/12/94	Schuette et al.	/	/	
	AG	5,591,494	1/7/97	Sato et al.	/	/	
	AH	5,968,611	10/19/99	Kaloyeros et al.	/	/	
	AI	6,159,871	12/12/00	Loboda et al.	/	/	
	AJ	5,461,003	10/24/95	Havemann et al.	/	/	
	AK	6,124,641	9/26/00	Matsuura	/	/	
KAD	AL	5,554,567	9/10/96	Wang	/	/	

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		Document Number	Date	Country	Class	Subclass	Translation	
							Yes	No
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	AN							

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)

KAD	AO	✓	Withmall, R. et al., "Matrix Reactions of Methylsilanes and Oxygen Atoms", Phys. Chem. 1988, pages 92, 594-602.
KAD	AP	✓	Joshi, A.M. et al., "Plasma Deposited Organosilicon Hydride Network Polymers as Versatile Resists for Entirely Dry Mid-Deep UV Photolithography", SPIE Vol. 1925, pages 709-720.
KAD	AQ	✓	Matsuura M. et al., "A Highly Reliable Self-planarizing Low-k Intermetal Dielectric for Sub-quarter Micron Interconnects", IEEE, pages 785-788.
KAD	AR	✓	Horie, O. et al., "Kinetics and Mechanism of the Reactions of O ^{(1)P} with SiH ₄ , CH ₃ SiH ₃ , (CH ₃) ₂ SiH ₂ , and (CH ₃) ₃ SiH", American Chemical Society 1991, pages 4393-4400.

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M122-1694SERIAL NO.
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U.S. PATENT DOCUMENTS

*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
UAD	AA	6,028,015	2/22/00	Wang et al.	—	—	
	AB	5,744,399	4/28/98	Rostoker et al.	—	—	
	AC	5,883,014	3/16/99	Chen et al.	—	—	
	AD	6,156,674	12/5/00	Li et al.	—	—	
UAD	AE	6,140,151	10/31/00	Akram	—	—	
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FOREIGN PATENT DOCUMENTS

		Document Number	Date	Country	Class	Subclass	Translation	
							Yes	No
	AM							
	AN							

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)

UAD	AO	✓	TEXT: Ralls, K. et al., "Introduction to Materials Science and Engineering", 1976 John Wiley & Sons, Inc., pp. 312-313.
UAD	AP	✓	Laxman, R. et al., "Synthesizing Low-K CVD Materials for Fab Use", Semiconductor Internatl., Nov. 2000, pp. 95-102 (printed from www.semiconductor-intl.com).
UAD	AQ	✓	Anonymous, "New Gas Helps Make Faster ICs", Machine Design, Vol. 71, Iss. 21, Nov. 4, 1999, p. 118.
UAD	AR	✓	IBM Technical Disclosure Bulletin, "Low-Temperature Deposition of SiO ₂ , Si ₃ N ₄ or SiO ₂ -Si ₃ N ₄ ", Volume Number 28, Issue Number 9, Page Number 4170.

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<div style="position: relative; height: 100px;"> <div style="position: absolute; top: 0; left: 0; width: 100%; height: 100%; border: 1px solid black; border-radius: 50%; text-align: center; color: white; font-weight: bold; font-size: 1.2em;"> OIPE JCT AUG 01 2001 PATENT & TRADEMARK OFFICE </div> </div>					LIST OF ART CITED BY APPLICANT <small>(Use additional sheets if necessary)</small>			
					APPLICANT Weimin Li et al.			
					FILING DATE RCE Filed Herewith		GROUP 1755	
U.S. PATENT DOCUMENTS								
*Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate		
	AA	App. 09/146,842 (as filed and amended)	Yin et al.			9/98		
	AB	App. 09/146,843 (as filed and amended)	Li et al.			9/98		
	AC	App. 09/030,618 (as filed and amended)	Mohsner et al.			2/98		
	AD	App. 09/234,233 (as filed and amended)	Li et al.			1/99		
	AE							
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FOREIGN PATENT DOCUMENTS								
	Document Number	Date	Country	Class	Subclass	Translation		
						Yes	No	
	AK							
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	AM							
	AN							
	AO							
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)								
KM	AP	ABSTRACT: Loboda, M. et al., "Using Trimethylsilane to Improve Safety, Throughput and Versatility in PECVD Processes", Electrochemical Society Meeting Abstract No. 358, 191 st Meeting, Montreal, Quebec, Vol. MA 97-1, 1997, page 454.						
KM	AQ	Julius Grant, "Hack's Chemical Dictionary", McGraw-Hill Book Company 1969, Fourth Edition, page 27.						
	AR							
EXAMINER <i>K. Dueda</i>				DATE CONSIDERED <i>8-5-02</i>				
*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.								

Form PTO-1449		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. M122-1694	SERIAL NO. 09/885,393		
<div style="display: flex; align-items: center;"> <div style="border: 2px solid black; border-radius: 50%; padding: 10px; text-align: center; margin-right: 10px;"> O I P E AUG 27 2001 PATENT & TRADEMARK OFFICE </div> <div> LIST OF ART CITED BY APPLICANT (Use several sheets if necessary) </div> </div>				APPLICANT Richard Holscher et al.			
				FILING DATE June 19, 2001		GROUP 1756	
U.S. PATENT DOCUMENTS							
*Examiner Initial	Document Number	Date	Name	Class	Subclass		
KAD	AA 5,314,724	05/24/94	Tsukune et al.	427	489		
KAD	AB 5,376,591	12/27/94	Maeda et al.	437	238		
KAD	AC 5,817,549	10/06/98	Yamazaki et al.	438	166		
KAD	AD 6,072,227	06/06/00	Yau et al.	257	642		
KAD	AE 6,001, 741	12/14/99	Alers	438	706		
KAD	AF 5,786,039	07/28/98	Brouquet	427	578		
	AG						
	AH						
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FOREIGN PATENT DOCUMENTS							
	Document Number	Date	Country	Class	Subclass	Translation	
	AM					Yes	No
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ATTY. DOCKET NO.
MI22-1694

SERIAL NO.
09/885,393

APPLICANT
Richard Holscher et al.

FILING DATE
June 19, 2001

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U.S. PATENT DOCUMENTS

*Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date if Applicable
KAD	AA 6,235,568	05/2001	Murthy et al.	438	231	
	AB 6,187,694	02/2001	Cheng et al.	438	947	
	AC 5,750,442	5/1998	Juengling	438	761	
	AD 6,114,255	9/2000	Juengling	438	763	
	AE 6,238,976	5/2001	Noble et al.	438	259	
	AF 6,008,121	12/1999	Yang et al.	438	637	
	AG 5,140,390	8/1992	Li et al.	357	23.7	
	AH 5,286,661	2/1994	de Fresart et al.	437	31	
	AI 6,184,151	2/2001	Adair et al.	438	743	
	AJ 6,225,217	5/2001	Usami et al.	438	637	
	AK 6,004,850	12/1999	Lucas et al.	438	301	
KAD	AL 6,140,677	10/2000	Gardner et al.	257	327	

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Document Number	Date	Country	Class	Subclass	Translation	
					Yes	No
AM						
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ATTY. DOCKET NO.
M122-1694

SERIAL NO.
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APPLICANT
Richard Holscher et al.

FILING DATE
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*Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date In Appropriate
KUD	AU 6,133,096	10/2000	Su et al.	438	264	
	AV 6,136,636	10/2000	Wu	438	231	
	AW 5,933,721	8/1999	Hause et al.	438	217	
	AX 5,981,368	11/1999	Gardner et al.	438	595	
	AY 6,159,804	12/2000	Gardner et al.	438	265	
	AZ 6,130,168	10/2000	Chu et al.	438	717	
	BA 6,235,591	5/2001	Balasubramanian et al.	438	275	
	BB 6,198,144	3/2001	Pan et al.	257	412	
	BC 5,801,399	9/1998	Hattori et al.	257	69	
	BD 5,994,730	11/1999	Shrivastava et al.	257	306	
	BE 6,040,619	3/2000	Wang et al.	257	649	
KUD	BF 6,060,765	5/2000	Maeda	257	635	

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	Document Number	Date	Country	Class	Subclass	Translation	
						Yes	No
BG							
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BJ							
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OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)

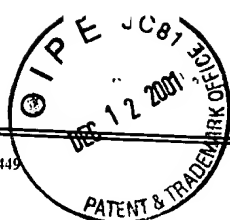
BL			
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*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date in Appropriate
KMD	BO	6,060,766	5/2000	Mehta et al.	257	639	
(KMD)	BP	6,133,613	10/2000	Yao et al.	257	639	
	BQ						
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							Yes	No
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				FILING DATE June 19, 2001	GROUP 1756

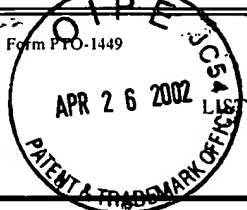
U.S. PATENT DOCUMENTS							
*Examiner Initial	Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate	
KAD	AA 6,268,282 B1	07/2001	Sandhu et al.	438	636		
	AB						
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U.S. PATENT DOCUMENTS							
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KMD	AA	6,087,267	06/00	Dockrey et al.	438	719	
KMD	AB	5,543,654	08/96	Dennen	257	386	
KMD	AC	5,656,330	08/97	Niyama et al.	427	255	
KMD	AD	5,872,035	02/99	Kim et al.	438	261	
KMD	AE	4,444,617	04/84	Whitcomb	156	643	
KMD	AF	6,071,799	06/00	Park et al.	438	595	
KMD	AG	5,691,212	11/97	Tsai et al.	437	24	
KMD	AH	6,187,657 B1	02/01	Xiang et al.	438	596	
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